

IN THE CLAIMS

1. (Amended) A method of producing a multi-layered wiring board comprising [the steps of]:  
    forming an insulating layer [made] of a photosensitive resin on a substrate for forming multi-layered wiring, and exposing and developing said insulating layer to form holes having a [predetermined shape] size;  
    depositing a curable resin onto said insulating layer having [said] the holes [formed therein in such a manner as to bury said] and filling the holes, and heating said curable resin to form a cured thin film of said curable resin on [the surface of] said insulating layer; and  
    removing said curable resin [in such a manner as to leave], leaving said cured thin film and [to form] via-holes having a [reduced opening] size reduced by said cured thin film from the size of the holes.

2. (Amended) [A] The method of producing a multi-layered wiring board according to claim 1, wherein said photosensitive resin is at least one member selected from the group consisting of an epoxy resin, an epoxy-modified acrylate resin, a cationic polymerization product of an epoxy resin, a

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phenol resin, a melamine resin, a carboxy-modified epoxy acrylate, and a cinnamate.

3. (Amended) [A] The method of producing a multi-layered wiring board according to claim 1, wherein said curable resin comprises one of a water-soluble resin [or] and a water-soluble cross-linking agent.

4. (Amended) [A] The method of producing a multi-layered wiring board according to claim 1, wherein said curable resin is at least one member selected from the group consisting of polymethylsiliceous siloxane, a melamine resin, an acrylate resin, and an epoxy resin.

5. (Amended) [A] The method of producing a multi-layered wiring board according to claim 1, wherein said curable resin contains rubber particles consisting of a butadiene-acrylonitrile copolymer, and [said method further comprises the step of] including chemically surface-roughening said cured thin film.

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A | 6. (Amended) [A] The method of producing a multi-layered wiring board according to claim 2, wherein said curable resin comprises one of a water-soluble resin [or] and a water-soluble cross-linking agent.

7. (Amended) [A] The method of producing a multi-layered wiring board according to claim 2, wherein said curable resin is at least one member selected from the group consisting of polymethylsiliceous siloxane, a melamine resin, an acrylate resin, and an epoxy resin.

8. (Amended) [A] The method of producing a multi-layered wiring board according to claim 3, wherein said curable resin contains particles of one of calcium carbonate [or] and polybutadiene rubber.

9. (Amended) [A] The method of producing a multi-layered wiring board according to claim 4, wherein said curable resin contains particles of one of calcium carbonate [or] and polybutadiene rubber.

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*Amend*

10. (Amended) [A] The method of producing a multi-layered wiring board including a plurality of stages of via-holes formed by repeating [said] the process [steps] of claim 1, wherein [said] the via-holes of upper stages [are so formed as to posses a greater degree of reduction] are more reduced in size than [said] the via-holes of lower stages.

**IN THE ABSTRACT**

Please replace the existing Abstract of the Disclosure with the appended Abstract of the Disclosure.

**REMARKS**

The foregoing changes are made to improve the form of the patent application. No new matter has been added and entry is respectfully requested.